

AMENDMENTS TO THE CLAIMS

Claim 1 (Original) A lead-free bump obtained by forming an Sn-Ag alloy film having a lower Ag content than that of an Sn-Ag eutectic composition by plating and reflowing the plated alloy film.

Claim 2 (Original) The lead-free bump according to claim 1, wherein the Ag content in the plated Sn-Ag alloy film is 1.6 to 2.6% by mass.

Claim 3 (Original) The lead-free bump according to claim 1, wherein the maximum temperature of the reflowing the plated alloy film is not higher than 240°C.

Claim 4 (Original) The lead-free bump according to claim 1, wherein the Ag content in the plated alloy film is adjusted to be lower than the Ag content of the Sn-Ag eutectic composition by controlling a composition of a plating bath and electrodeposition conditions.

Claim 5 (Original) The lead-free bump according to claim 1, wherein the amount of α -rays emitted from a surface is not higher than 0.02 cph/cm².

Claims 6-17 (Cancelled)